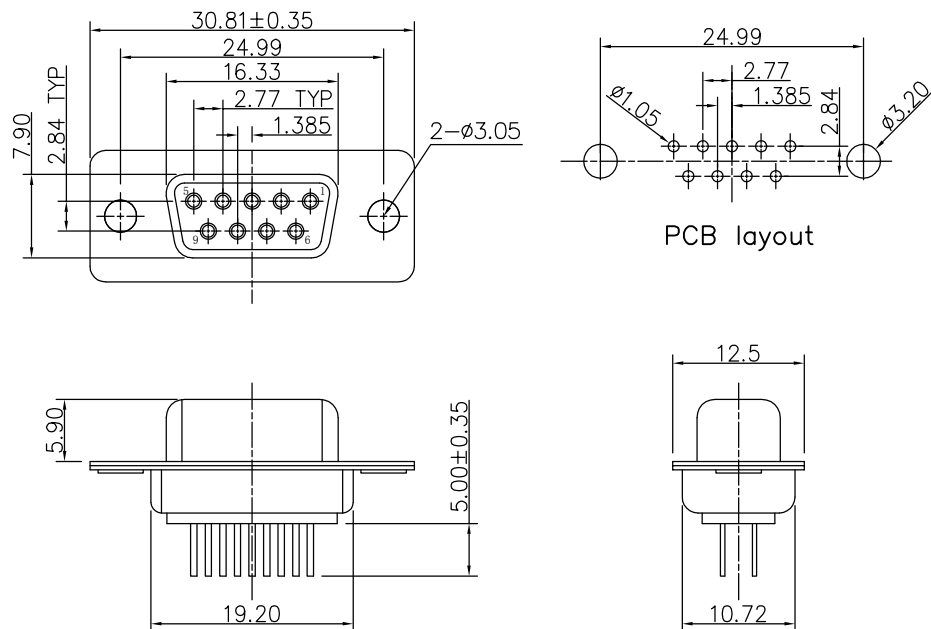
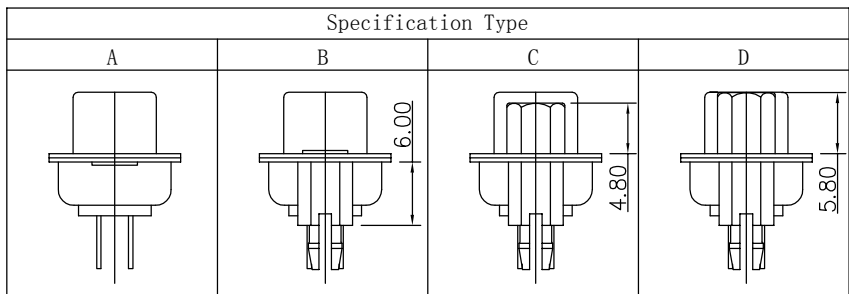


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements

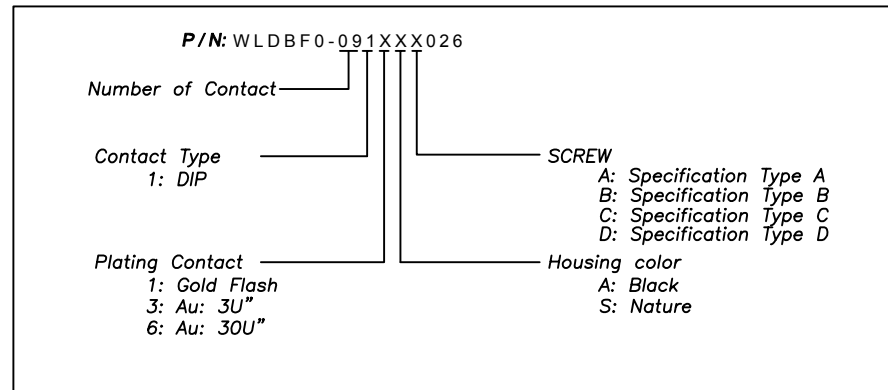


PCB layout

- NOTE
- MATERIAL:
 - INSULATOR: PBT+30% GLASS FIBER UL94V-0
COLOR:BLACK
 - TERMINAL: COPPER ALLOY BRASS T=0.20±0.02mm
GOLD FLASH ON CONTACT AREA AND TIN 80U" ON SOLDER TAIL; NICKEL:30U" ON THE BASE
 - SHELL: FRONT SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Ni50u" ;
REAR SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Tin80u"
 - BOARD LOCK: COPPER ALLOY, PLATING: Cu50u"/Ni40u"
 - SCREW: STEEL, PLATING: Cu50u"/Ni40u"
 - SALT SPRAY: PLATING GOLD, 24H; OTHER PART: 12H .
 - ELECTRICAL:
 - INSULATOR RESISTANCE: 1000MEGOHMS MIN AT 500V DC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC R.M.S
 - VOLTAGE TATING: 40V AC (RMS) CONTINUOUS MAX.
 - CURRENT RATING: 3A.
 - CONGTACT RESISTANCE: 30 MILLIOHMS MAX.
 - MECHANICAL
 - INSERTION/EXTRACTION FORCE PER CONTACT: 3.0Kgf Max
0.3Kgf Min.
 - ENVIRONMENTAL
 - TEMPERATURE RANGE:-55°C TO + 105°C.



ORDER INFORMATION



REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	21.01.13	WLDBF0-091XXX026	ENDE05	
A1	ADD MATERIAL THICK AND PLATING	23.04.27	UNIT:mm	0.00±0.25	X'±3'	DESIGNER	Ou_jian	21.01.13	TITLE:		REV: A0 SHEET: 1/1
			SIZE: A4	0.000±0.10	X'X' ±2'	DRAWN	Hou-lanxuan	21.01.13	DP 09F DIP		

WanLian Technology Co., Ltd